

FIG. 1

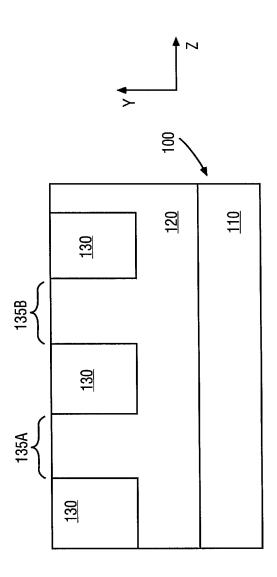


FIG. 2

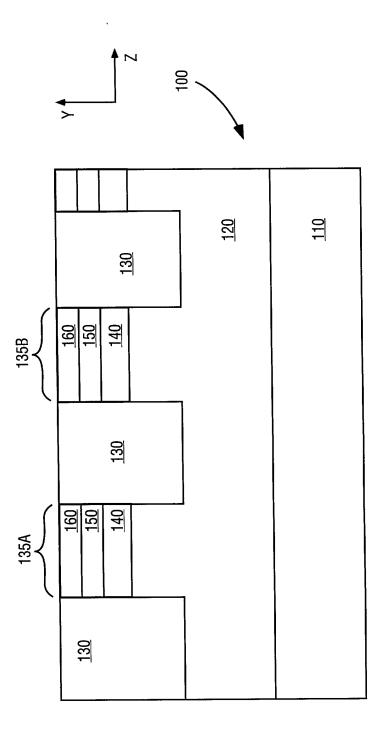


FIG. 3

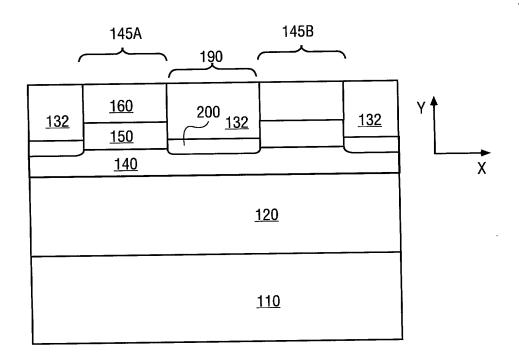


FIG. 4

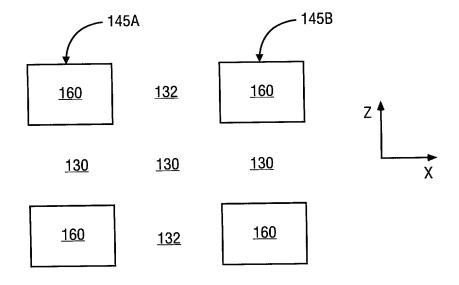


FIG. 5

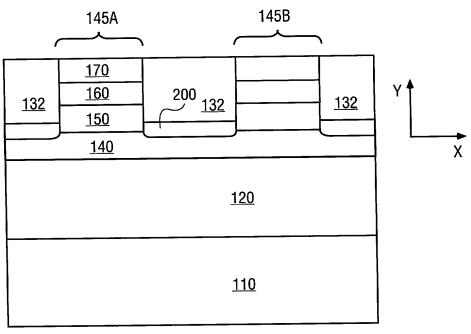


FIG. 6

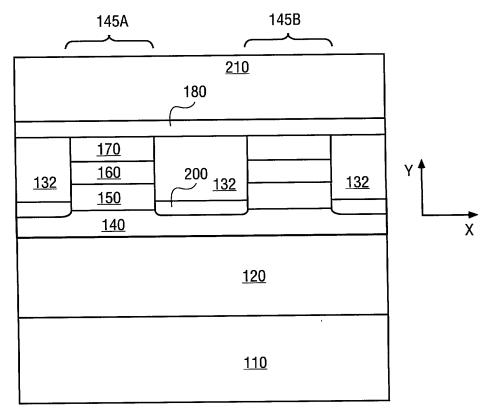
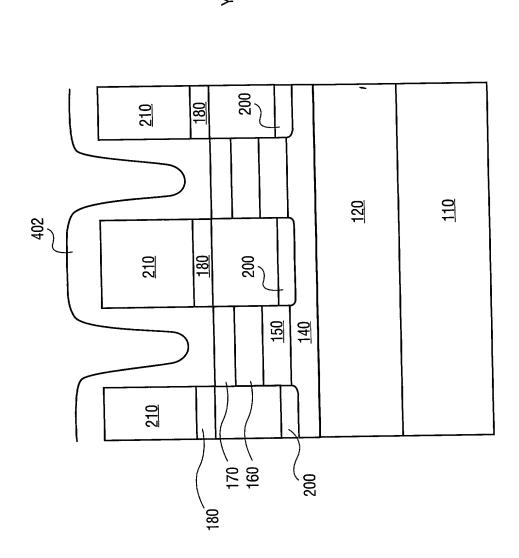


FIG. 7

<u> 되</u>다. 



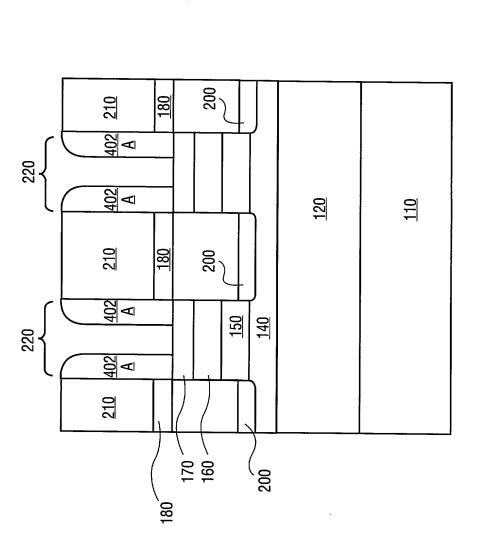
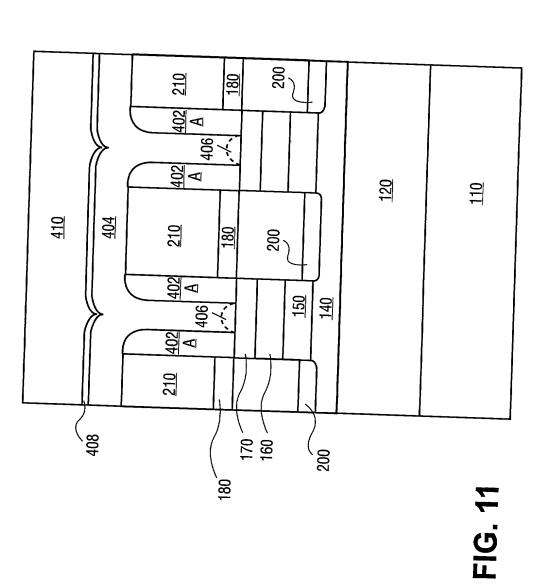


FIG. 1



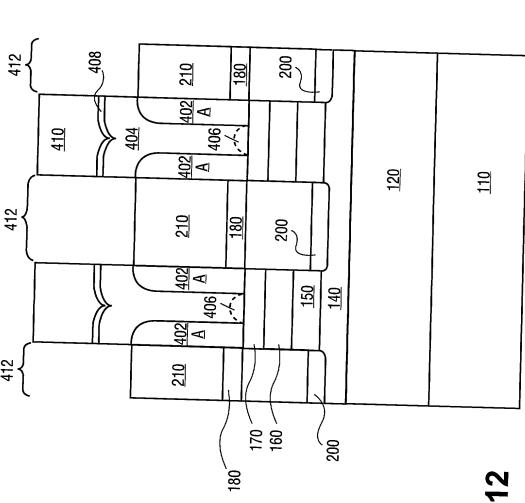
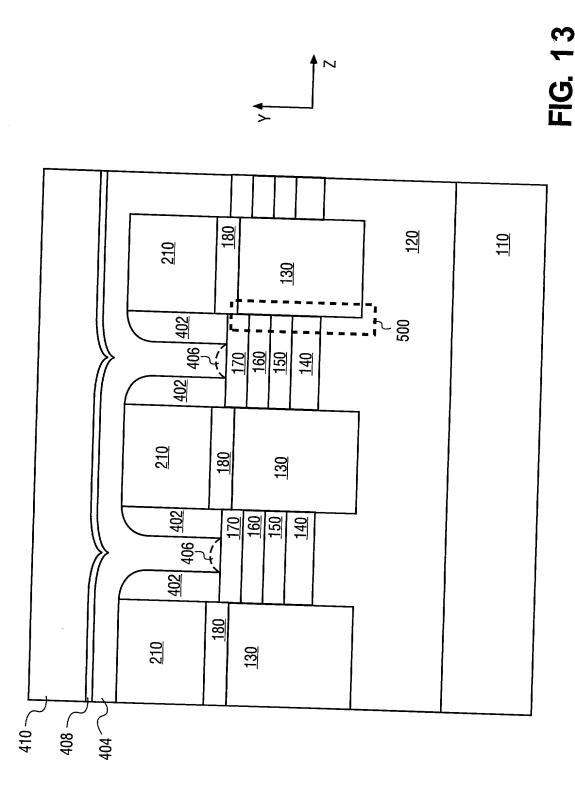
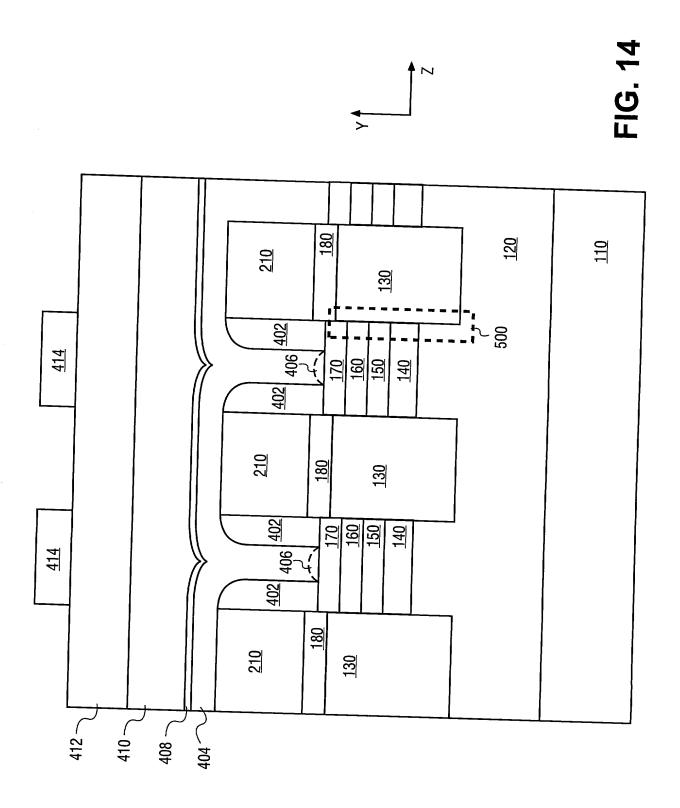


FIG. 12





FORM A DIELECTRIC ON A CONTACT, THE CONTACT FORMED ON SUBSTRATE. FORM AN OPENING THROUGH THE DIELECTRIC EXPOSING THE CONTACT. OPTIONALLY, FORM A SPACER WITHIN THE OPENING AND OPTIONALLY CONFORMALLY FORM THE SPACER ON THE DIELECTRIC AND WITHIN THE OPENING; AND FURTHER OPTIONALLY ANISOTROPICALLY ETCH THE SPACER FROM THE DIELECTRIC USING AN AGENT SELECTIVE FOR THE SPACER. FORM PROGRAMMABLE MATERIAL WITHIN THE OPENING, THE PROGRAMMABLE MATERIAL ON THE CONTACT. FORM A CONDUCTOR TO THE PROGRAMMABLE MATERIAL. OPTIONALLY, FORM A BARRIER BETWEEN THE PROGRAMMABLE MATERIAL AND THE CONDUCTOR. OPTIONALLY, FORM AN ISOLATION DEVICE BETWEEN THE CONTACT AND A SIGNAL LINE. FORM A DIELECTRIC ON THE CONDUCTOR. FORM A VIA IN THE DIELECTRIC TO THE CONTACT. FILL THE VIA WITH CONDUCTIVE MATERIAL. FORM A CONDUCTOR ON THE DIELECTRIC.

FIG. 15

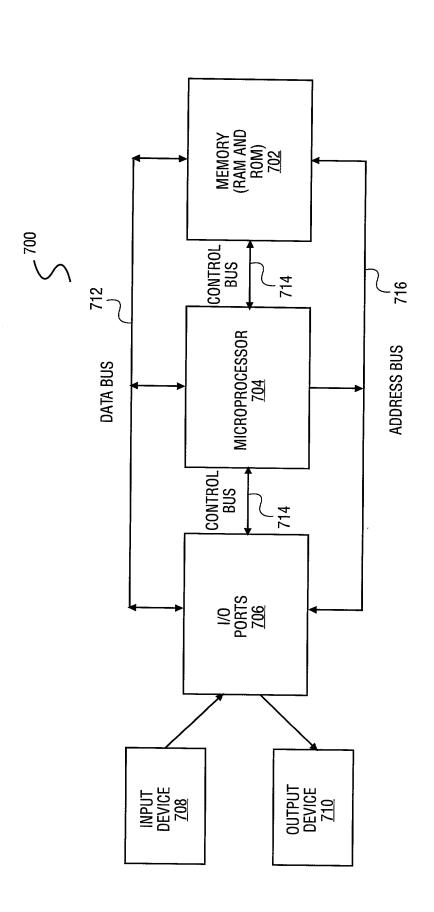


FIG. 16